

Thermoelectric Module



Scope

This specification is applied to Multicomp thermoelectric modules
Revision of these specifications is carried out after consent

Specifications

Parameters		Remarks
Internal resistance	1.9 Ω \pm 10%	Note-1
I max.	15.4 A	Note-2
V max.	35.8 V	Note-3
-	Th = 25°C	-
Q max.	340 W	Note-4
Δ T max.	68°C	Note-5
Solder melting point	138°C	Note-6
Maximum compress	1 MPa	Note-7

Note-1 : Measured by AC 4 - terminal method at 25°C

Note-2 : Maximum current at Δ T max.

Note-3 : Maximum voltage at Δ T max.

Note-4 : Maximum cooling capacity at I max. V max. and Δ T = 0°C

Note-5 : Maximum temperature difference at I max. V max. and Q = 0 W
(Maximum parameters are measured in a vacuum 1.3 P)

Note-6 : The solder melting point of thermoelectric module

Note-7 : Recommended maximum compression (not destruction limit)

Recommendations:

High cooling capacity from a small surface and long lifetime in power cycling applications with change of current polarity

Operation temperature up to 90°C for long lifetime; up to 110°C for short periods

With operation current close to 0.5 I max. extremely high COP (coefficient of performance possible)

Preferable application; high cooling capacity at high temperatures / cycling

Epoxy sealed for moisture protection

Specification Table

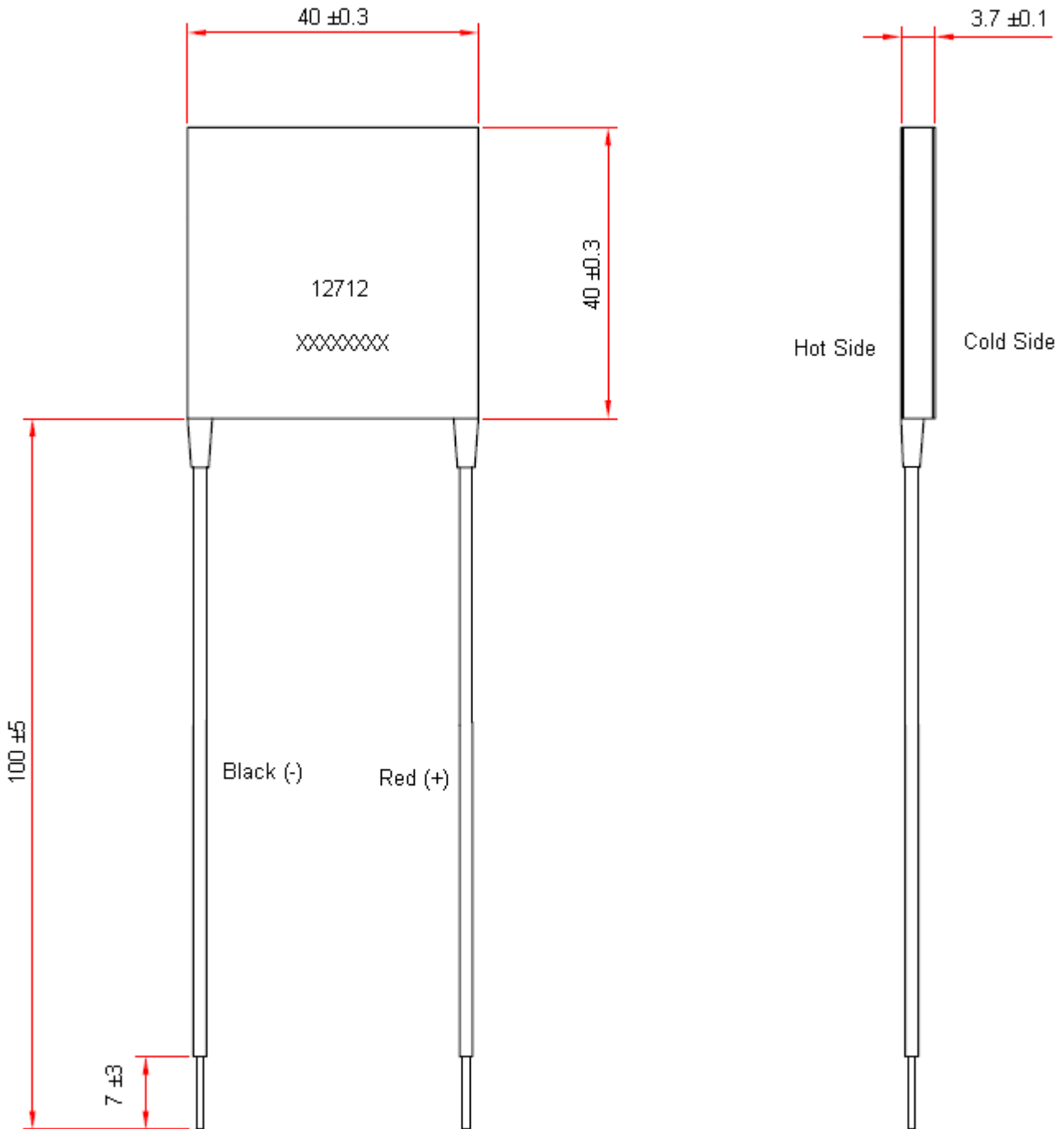
Thot = 27°C

I max. (A)	U max. (V)	Qc max. W	dT max. °C	A	B	H	Part Number
15.4	35.8	340	68	50	50	3.9	MCHPE-288-14-06-E

Dimensions : Millimetres

Thermoelectric Module

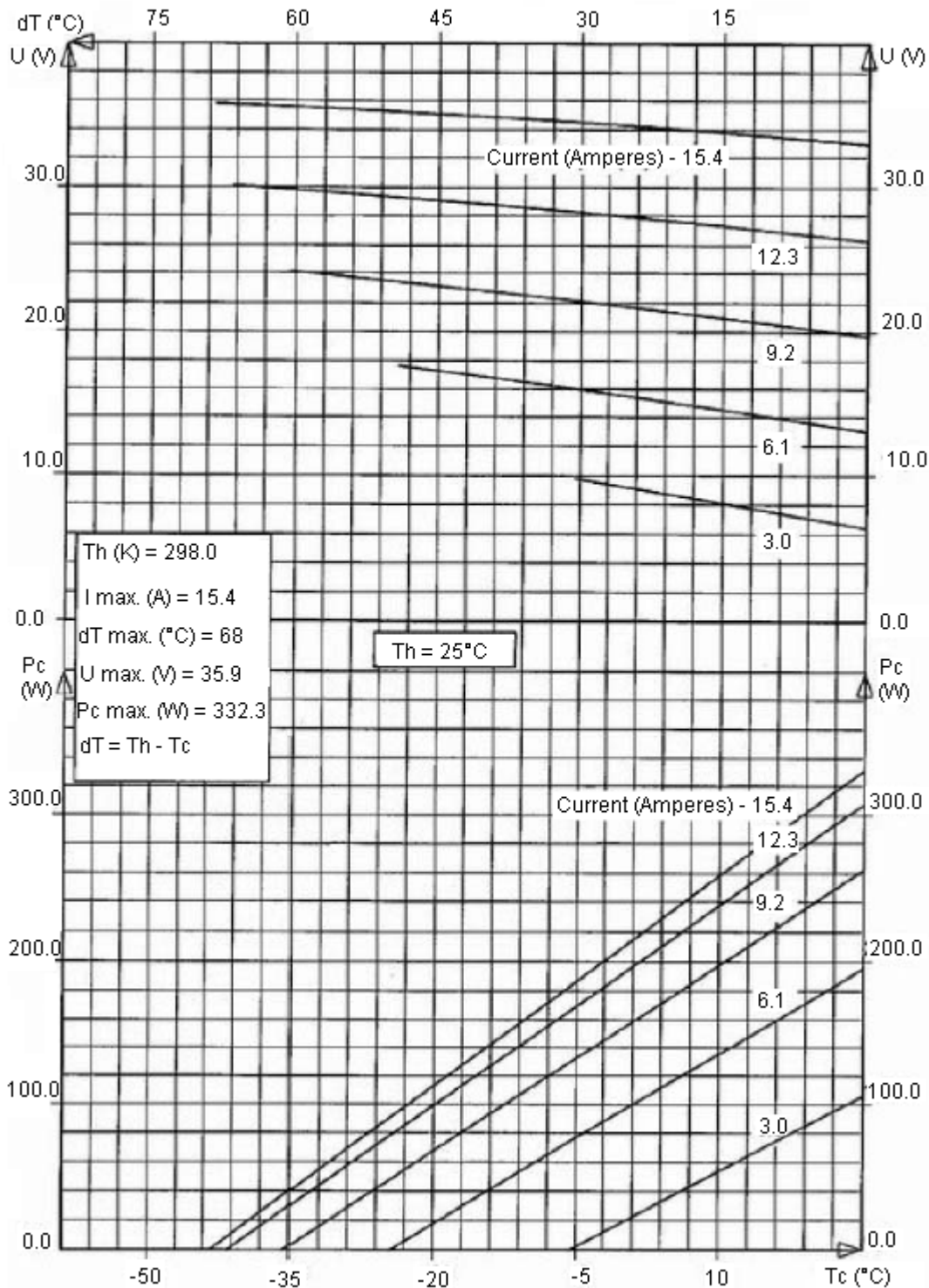
Outline Drawing



Dimensions : Millimetres

Thermoelectric Module

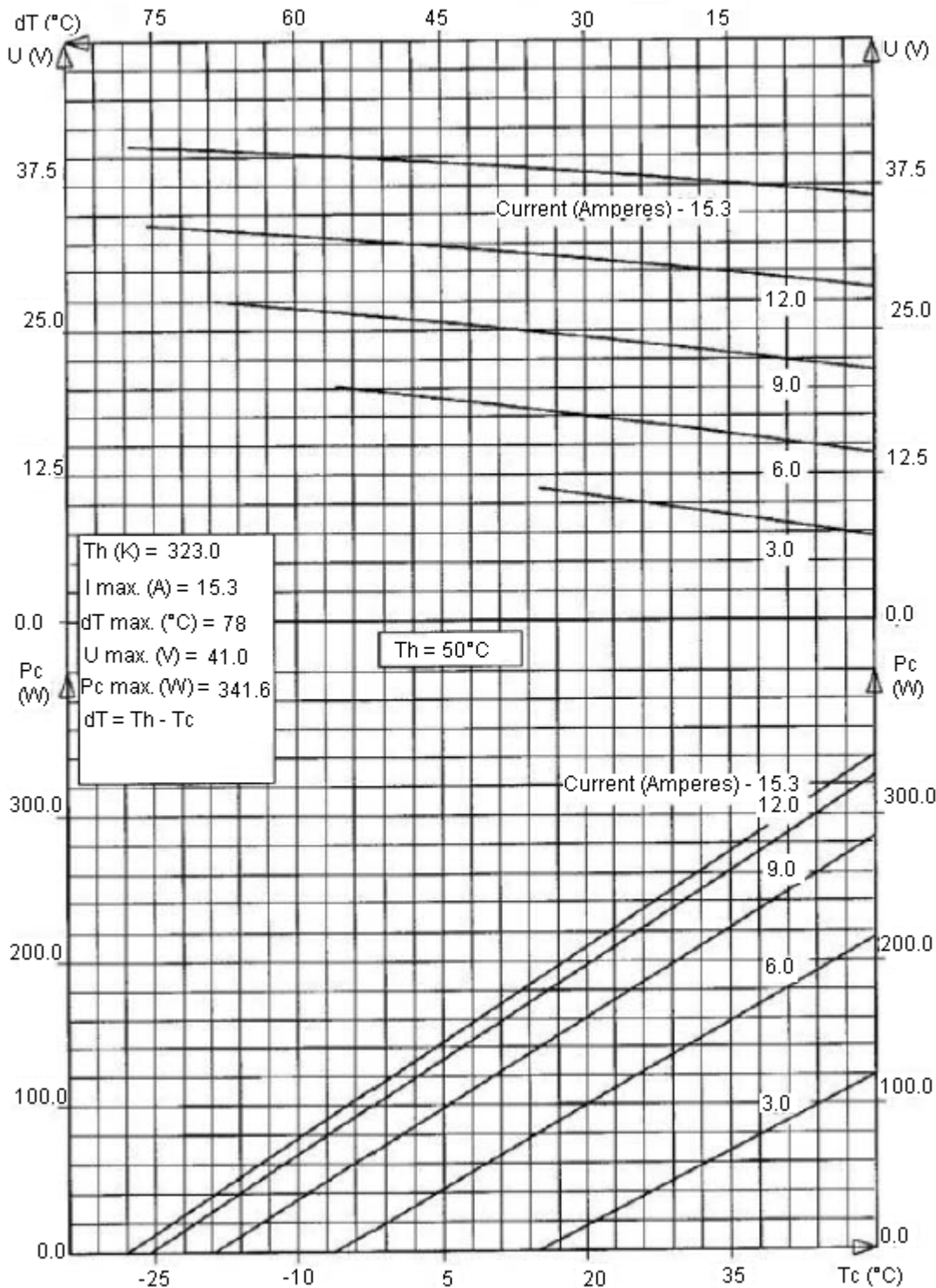
Performance Graph (298K)



Thermoelectric Module



Performance Graph (323K)



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